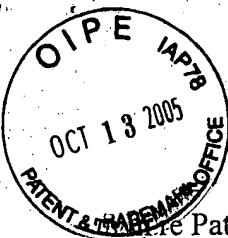


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Patent Application:
Rajeev Joshi et al.

Serial No.: 10/618,113

Filed: July 11, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 8697

Group Art Unit: 2829

Examiner: Zarnecke, David A.

Mail Stop Non-Final Response
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

COPY

Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION UNDER
37 C.F.R. §§ 1.111 AND 1.116

In response to Notice of Non-Compliant Amendment mailed on June 9, 2005, and in further response to the Office Action mailed February 1, 2005, Applicant requests reconsideration of this application in light of the following amendments and remarks.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to:
Commissioner for Patents, Alexandria, VA 22313-1450, on this 10 day of June 2005.

Signed: Erin Gauthier

6/16/2005